



ML-8150A Green Pulse Laser Welder

- · For solder-less joining of semiconductor substrate
- SHG laser can weld copper wire directly onto a semiconductor substrate without using solder
- Combination of YAG fundamental laser and SHG laser realizes welding of thick copper plates; which is difficult to weld by a conventional way
- SHG laser is the best solution for welding copper and gold
- Copper and gold are materials with high reflectance so that those are known as hard-to-weld materials
- · Wavelength of SHG laser is 532 nm which is a half of fundamental laser (1064 nm) and that makes laser absorptance to copper and gold 4.5 to 20 times higher than fundamental laser
- · Even copper and gold does not reflect SHG laser

TYPICAL APPLICATIONS





-0

- 6



Welding of mount parts onto PCB without solder



Penetration of 1.26 mm in CuSn6

KEY FEATURES

- Maximum power is 5 W! Its power gets much stronger than ML-8050A with 2 W
- · Beam quality is up and power density is nine times higher than the existing model. (190 kW/mm² @1.5 kW)
- High-speed, Welding shortens takt time
- Real-time power feedback control feature supports stable laser output
- Air cooling method is employed; no additional heat exchanger is necessary



Welding of copper on PCB



Penetration of 1.26 mm in CuSn6

TECHNICAL SPECIFICATIONS

Oscilla tor	Technical specifications	5 W
	Weldheads	4 JP / 1.5 kW
	Available for	0.20 to 5.00 ms (0.02ms step)
	Offset	1 to 30 pps
	Front head 40 mm lower (other steps upon request)	532 nm
	Head selection	Optical fiber / Two energy sharing at maximum
Power supply	Camera	200/220/240 VAC +10% -15% 50/60 Hz Single phase
	Shielding gas	7A / 2.0 kVA
	Maximum output	15A
	Beam quality	RS-485
	Pulse width	Air cooling
	Pulse width resolution	5 to 30 °C / 85% or below
Weight ML-8150A (Power supply / Oscillator)		approx. 175 kg

DRAWINGS









